
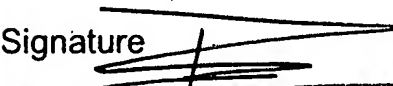


ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of Invention	Aluminum Pad Power Bus and Signal Routing for Integrated Circuit Devices Utilizing Copper Technology Interconnect Structures																												
<p>Application Number: 10/675258 </p> <p>Confirmation Number: 4017</p> <p>First Named Applicant: Seung Kang</p> <p>Attorney Docket Number: 075903-218</p> <p>Art Unit: 2816</p> <p>Search string: (5148263 or 6225207).pn.</p> <p>US Patent Documents</p> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td>TL</td><td>1</td><td>5148263</td><td>1992-09-15</td><td>Hamai</td><td></td><td></td><td></td></tr><tr><td>TL</td><td>2</td><td>6225207</td><td>2001-05-01</td><td>Parikh</td><td></td><td></td><td></td></tr></tbody></table> <p>Signature </p> <table border="1"><tr><td>Examiner Name</td><td>Date</td></tr><tr><td></td><td>01/14/05</td></tr></table>		init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass	TL	1	5148263	1992-09-15	Hamai				TL	2	6225207	2001-05-01	Parikh				Examiner Name	Date		01/14/05
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